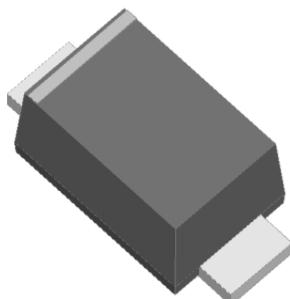


Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 20 to 200 V

Forward Current - 3.0A


FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SOD-123FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 15mg 0.00048oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	K32	K34	K36	K38	K310	K312	K315	K320	Units		
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V		
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V		
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V		
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0							A			
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	80							A			
Max Instantaneous Forward Voltage at 3 A	V_F	0.55		0.70		0.85		0.95		V		
Maximum DC Reverse Current $T_a = 25^\circ C$ at Rated DC Reverse Voltage $T_a = 100^\circ C$	I_R	0.5 10		0.3 5						mA		
Typical Junction Capacitance ⁽¹⁾	C_j	250		160						pF		
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	80							°C/W			
Operating Junction Temperature Range	T_j	-55 ~ +125							°C			
Storage Temperature Range	T_{stg}	-55 ~ +150							°C			

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C.

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

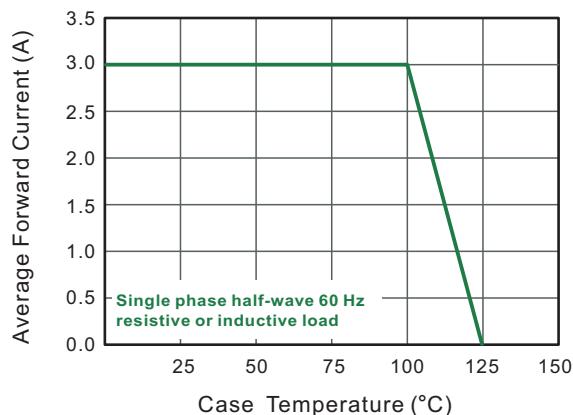


Fig.2 Typical Reverse Characteristics

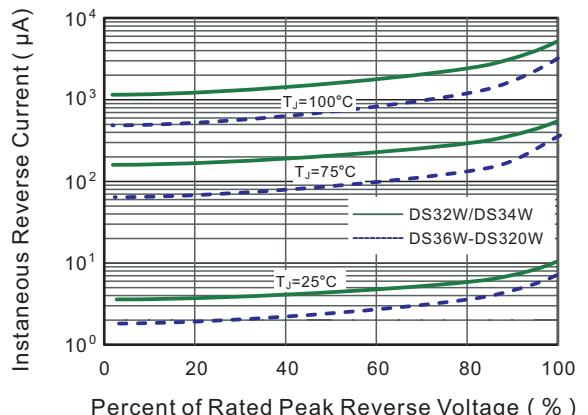


Fig.3 Typical Forward Characteristic

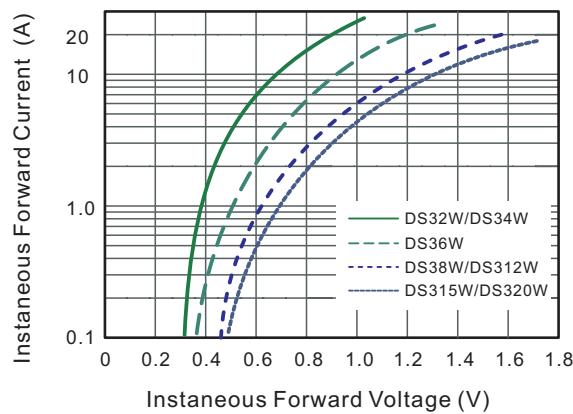


Fig.4 Typical Junction Capacitance

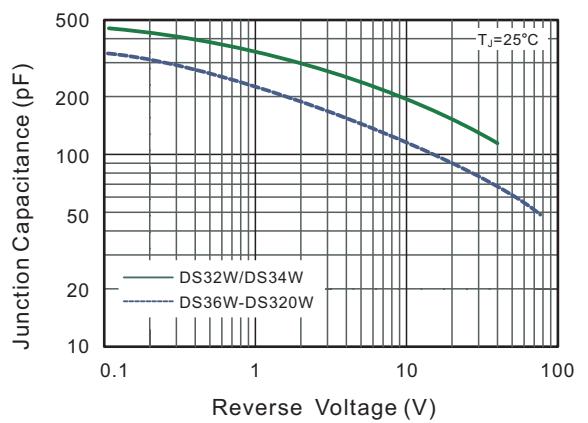


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

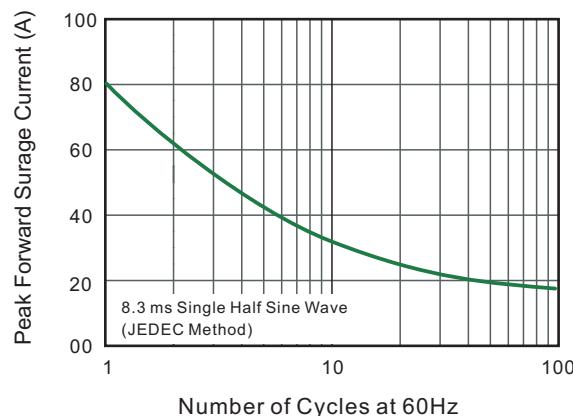
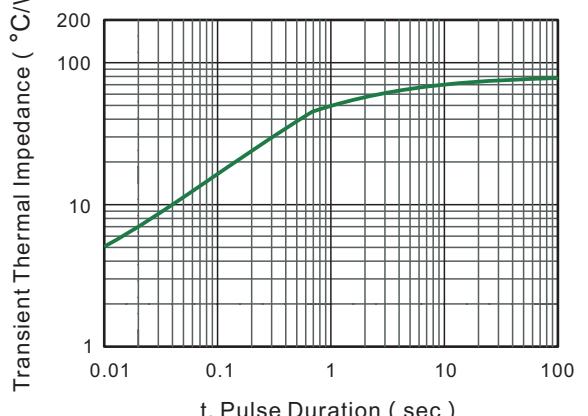
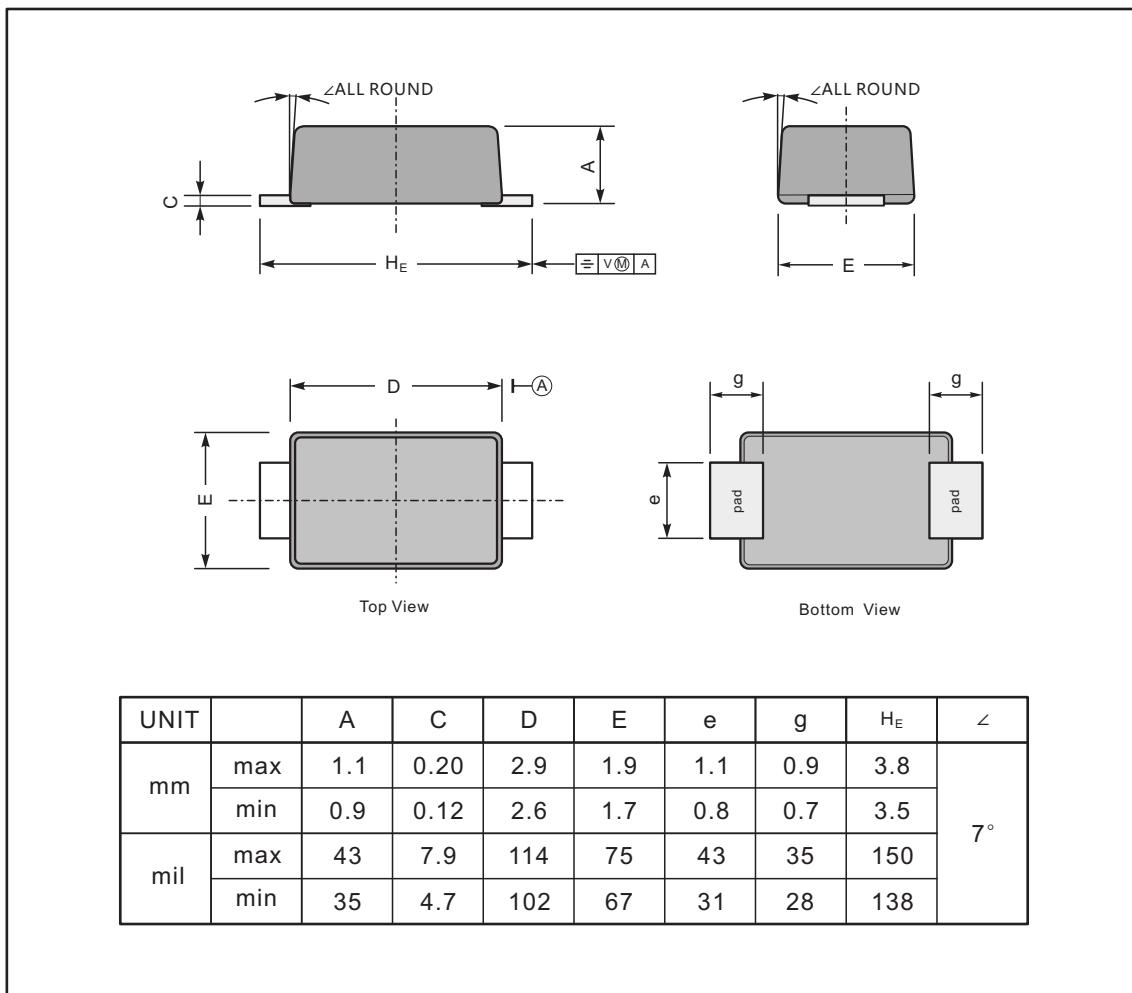


Fig.6- Typical Transient Thermal Impedance



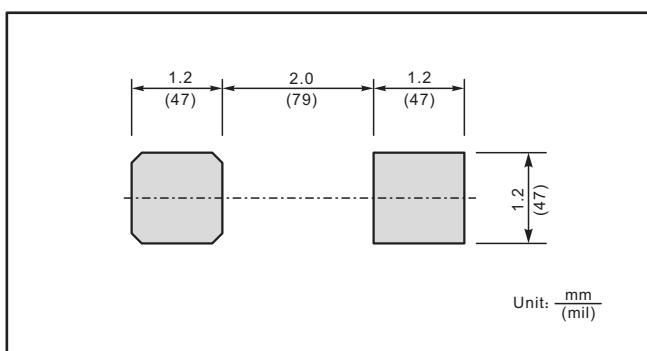
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads



UNIT		A	C	D	E	e	g	H_E	\angle
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	7°
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size



Marking

Type number	Marking code
K32	K32
K34	K34
K36	K36
K38	K38
K310	K310
K312	K312
K315	K315
K320	K320